

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-22 (Canceled).

Claim 23 (Currently Amended): A method for manufacturing an electronic part in which a layer having a uniform thickness is formed, the method comprising:

forming a power supply film on a surface of a support member;

forming at least one conductor portion by plating using the power supply film as an electrode;

bringing an insulating sheet attached on a copper foil into contact with the at least one conductor portion from above;

pressing by a pressurizing means ~~the second support member including the copper foil together~~ with the insulating sheet up to ~~[[the]]~~ a height of the at least one conductor portion ~~using said at least one conductor portion~~; and

removing said power supply film.

Claim 24 (Previously Presented): A method for manufacturing an electronic part according to claim 23, wherein said at least one conductor portion and said insulating sheet are detached from said surface, after making the height of said insulating sheet equal to the height of said at least one conductor portion.

Claim 25 (Previously Presented): A method of manufacturing an electronic part according to claim 23, wherein said support member is a substrate of said electronic part.

Claim 26 (Previously Presented): A method for manufacturing an electronic part according to claim 24, wherein a B-stage sheet is used as said insulating sheet.

Claim 27 (Previously Presented): A method for manufacturing an electronic part according to claim 25, wherein a B-stage sheet is used as said insulating sheet.

Claim 28 (Previously Presented): A method for manufacturing an electronic part according to claim 24, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 29 (Previously Presented): A method for manufacturing an electronic part according to claim 25, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 30 (Previously Presented): A method for manufacturing an electronic part according to claim 24, wherein heating is performed in addition to said pressing.

Claim 31 (Previously Presented): A method for manufacturing an electronic part according to claim 25, wherein heating is performed in addition to said pressing.

Claim 32 (Previously Presented): A method for manufacturing an electronic part according to claim 26, wherein heating is performed in addition to said pressing.

Claim 33 (Previously Presented): A method for manufacturing an electronic part according to claim 27, wherein heating is performed in addition to said pressing.

Claim 34 (Previously Presented): A method for manufacturing an electronic part according to claim 28, wherein heating is performed in addition to said pressing.

Claim 35 (Previously Presented): A method for manufacturing an electronic part according to claim 29, wherein heating is performed in addition to said pressing.